

DMF-UG 2017

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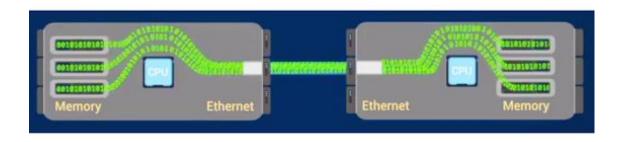
State of the Tape Storage Industry

- Technology Roadmap
 - RoCE interface
 - Head design update
 - Track v Linear Density
 - Investments required to meet the coming challenges
 - Some important changes to the supply chain
 - Tape Format roadmap
- Spectra Product Roadmap
 - Performance Improvements
 - Power Improvements
 - Increased flexibility



State of the Tape Storage Industry - Technology

Ethernet Connected Drives



- RoCE (RDMA over Converged Ethernet).
- Lower Cost infrastructure.
- Common Infrastructure.
- Higher Bandwidth
- Flexible Data Path and Management.

Future drives will release with RoCE. Release date to be determined



Tape Drives and Head Development

- Current Tape Drive Technology Based on GMR.
 - LTO7, T10000D, TS1150, T10000E (HDD's stopped using GMR in 2004)
- GMR has reached its density limits.
- TMR provides a 4x improvement in signal sensitivity. Less susceptible to noise and media discrepancies.
- TMR Heads run cooler than GMR.
 - Benefits media and data integrity.
- IBM TS1155 and LTO-8 will be based on TMR
- Tape has 13 yrs of TMR development to leverage



Capital Investment – The reality

TMR Requires Major Manufacturing Re-Investment

- *\$10-15 million in capital retooling per fab (estimated)
 - Canon Anelva vacuum deposition system cost \$7-8 million alone.
- *\$10-13M yearly production run rate cost (estimated)



TMR Requires Major Re-Engineering

- Head characteristics are substantially different than GMR
- IBM has had to pioneer new tech to make it work.
- It took IBM 8+ years to make it work in partnership with Hitachi/WD whom had experience with the technology.
- It will be the same for any manufacturer who make tape drives



^{*} Note "industry analyst predictions"



Supply Chain update

Drive Head Manufacturers





123,000 Heads Per Year



Heads Per Year

Tape Drive Manufacturers

Drive Heads

3,000 Per Year



Oracle® T10K Drives

3,000 Per Year

Drive Heads 120,000 Per Year



HP LTO Drives

120,000 Per Year



108,000 Per Year



IBM LTO Drives

100,000 Per Year

IBM TS Drives

8,000 Per Year



Supply Chain update

Drive Head Manufacturers





2,500 Heads Per Year



228,000 Heads Per Year

Tape Drive Manufacturers

Drive Heads

2,500 Per Year



Oracle® T10K Drives

2,500 Per Year



HP LTO Drives

120,000 Per Year



Drive Heads

108,000 Per Year

Drive Heads 120,000 Per Year



100,000 Per Year

IBM TS Drives

8,000 Per Year



228,000

Combined

IBM

Heads

IBM Tape Drive History and Roadmaps

LTO Generations	LTO-6	LTO-7	LTO-8	LTO-9
New Format Capacity (Native)	2.5 TB (L6)	6 TB (L7)	Up to 12 TB (L8)	Up to 25 TB (L9)
Other Format Capacities (Native)	1.5 TB (L5) (800 GB L4 R/O)	2.5 TB (L6) (1.5 TB L5 R/O)	6 TB (L7) (2.5TB L6 R/O)	Up to 12 TB (L8) (6 TB L7 R/O)
Native Data Rate	160 MB/s	300 MB/s	Up to 472 MB/s	Up to 708 MB/s

2012 2015

2011 2014

TS1100 Generations	TS1140	TS1150	TS1155	TS1160	TS1170
Max Native Capacity (media type)	4 TB (JC)	10 TB (JD) 7 TB (JC)	15-17 TB (JD) TBD (JC)	18-20 TB (JE) 15-17 TB (JD) 10-12 TB (JC)	30-40 TB (JE) 15-17 TB (JD) 10-12 TB (JC)
Native Data Rate	250 MB/s	360 MB/s	360 MB/s	Up to 500 MB/s	Up to 1000 MB/s
Attachment	FC-8	FC-8	FC-8, 10 GigE (RoCE, iSCSI)	FC-16, 25 GigE (RoCE, iSCSI)	TBD

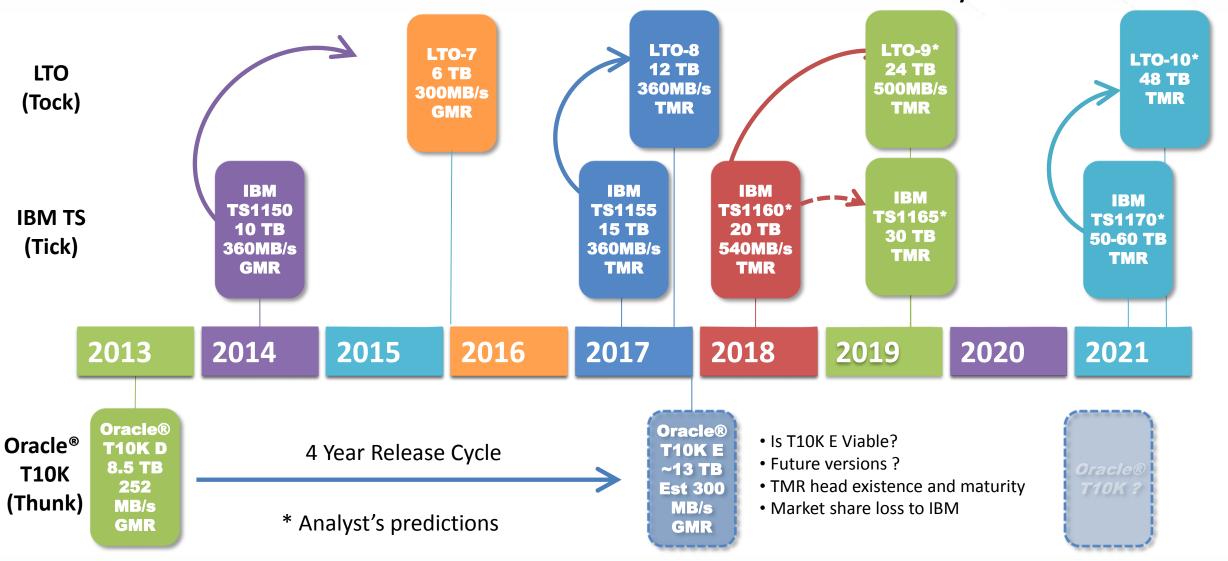
Drive roadmap reflects continued strong investment

- LTO-7 GA 6TB and 32 channel
- Enterprise to ship 15+TB on existing media
- LTO-8 back on cadence and targeting 12TB



State of the Tape Storage Industry - Tape Technology Roadmap

TS11x0 & LTO now on a 2 year cadence





Conclusions

- TMR Technology will introduce a step change in density and performance.
- Capacity without throughput creates bottlenecks.
 - TS11x0 technology has increased capacity and throughput for multiple generations.
 - Can the T10K keep up?
- Oracle lost its drive head business to IBM.
 - Needs to amortize \$20 \$30 million factory op-ex and new capital investment over 2,500 heads annually.
 - Oracle currently on a 4 year drive release cycle, IBM on a two year release cycle.
 - Uncertain roadmap beyond T10000D STILL
- IBM has been working with TMR for more than 8 years.
 - Will release the first TMR based drive in 2017
 - TS1155 will use same JD media at a lower price point with up-format
 - IBM's Tick-Tock strategy releases 1 drive a year
- Everything we hear from various sources
 - Oracle will exit the drive business.
 - What about Libraries ?



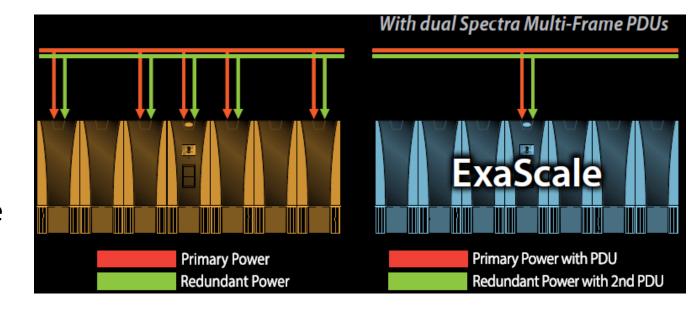




New Dual AC Power and Spectra Multi-Frame PDU

New Power Distribution Unit (PDU)

- One power drop for support of all frames.
- No need for multiple power drops.
- Similar to SL8500
- New Dual AC Power Support
- Complete support for out-of-phase dual power.
- No need for in-phase power.
- Lower installation time and costs.





Power Distribution Unit

Can take power the same as some other libraries



Delta Wiring

- Requires one three-phase input for each system PDU.
- 200–240 VAC, line-to-line, three-phase, 40 Amps, 50–60
 Hz (mostly used in the United States).

Wye Wiring

- Requires one three-phase input for each system PDU.
- 200–240VAC, line-to-neutral, three-phase, 24 Amps, 50–
 Hz (mostly used in Europe).

Optional Web Enabled Power Meter

Enables load power balancing across frames



Tri-media - Three Different Tape Technologies in the same library

- Spectra began with dual-tape technology combining LTO with IBM® TS technology in the same library.
 - Now including Oracle® T10000X technologies.
- Spectra's ExaScale Edition tri-media feature will allow migrating or integrating your existing T10000X media & drives.





Product Roadmap

PDU SlotiQ Dual AC MedialQ **Mixed Media** TS1155 LT08 **T10K CY17**

TS1160

Advanced Queueing

2.0 HAX Column

CY18



Custom Skins

The range of possibilities for customizing your ExaScale TFinity are almost boundless. Organizations can graphically customize panels nearly any way they would like.







Society's Genome

